

# BS107A

## Small Signal MOSFET

250 mA, 200 V, N-Channel TO-92

### Features

- AEC-Q101 Qualified and PPAP Capable
- This is a Pb-Free Device\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	200	Vdc
Gate-Source Voltage	$V_{GS}$	$\pm 20$	Vdc
– Continuous	$V_{GSM}$	$\pm 30$	Vpk
– Non-repetitive ( $t_p \leq 50 \mu s$ )			
Drain Current	$I_D$	250	mA dc
Continuous (Note 1)	$I_{DM}$	500	
Pulsed (Note 2)			
Total Device Dissipation @ $T_A = 25^\circ C$ Derate above $25^\circ C$	$P_D$	350	mW
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	$-55$ to $150$	$^\circ C$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The Power Dissipation of the package may result in a lower continuous drain current.
2. Pulse Test: Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2.0\%$ .

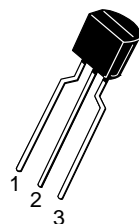
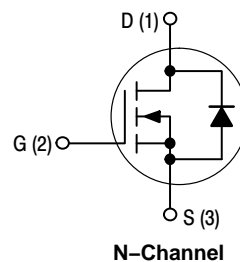


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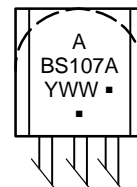
250 mAmps, 200 Volts

$$R_{DS(on)} = 6.4 \Omega$$



TO-92  
CASE 29-11  
STYLE 30

### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping
BS107ARL1G	TO-92 (Pb-Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# BS107A

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Zero-Gate-Voltage Drain Current ( $V_{DS} = 130\text{ Vdc}$ , $V_{GS} = 0$ )	$I_{DSS}$	–	–	30	nAdc
Drain-Source Breakdown Voltage ( $V_{GS} = 0$ , $I_D = 100\text{ }\mu\text{Adc}$ )	$V_{(BR)DSX}$	200	–	–	Vdc
Gate Reverse Current ( $V_{GS} = 15\text{ Vdc}$ , $V_{DS} = 0$ )	$I_{GSS}$	–	0.01	10	nAdc

### ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage ( $I_D = 1.0\text{ mAdc}$ , $V_{DS} = V_{GS}$ )	$V_{GS(Th)}$	1.0	–	3.0	Vdc
Static Drain-Source On Resistance BS107 ( $V_{GS} = 2.6\text{ Vdc}$ , $I_D = 20\text{ mAdc}$ ) ( $V_{GS} = 10\text{ Vdc}$ , $I_D = 200\text{ mAdc}$ ) BS107A ( $V_{GS} = 10\text{ Vdc}$ ) ( $I_D = 100\text{ mAdc}$ ) ( $I_D = 250\text{ mAdc}$ )	$r_{DS(on)}$	– – – –	– – 4.5 4.8	28 14 6.0 6.4	$\Omega$

### SMALL-SIGNAL CHARACTERISTICS

Input Capacitance ( $V_{DS} = 25\text{ Vdc}$ , $V_{GS} = 0$ , $f = 1.0\text{ MHz}$ )	$C_{iss}$	–	60	–	pF
Reverse Transfer Capacitance ( $V_{DS} = 25\text{ Vdc}$ , $V_{GS} = 0$ , $f = 1.0\text{ MHz}$ )	$C_{rss}$	–	6.0	–	pF
Output Capacitance ( $V_{DS} = 25\text{ Vdc}$ , $V_{GS} = 0$ , $f = 1.0\text{ MHz}$ )	$C_{oss}$	–	30	–	pF
Forward Transconductance ( $V_{DS} = 25\text{ Vdc}$ , $I_D = 250\text{ mAdc}$ )	$g_{fs}$	200	400	–	mmhos

### SWITCHING CHARACTERISTICS

Turn-On Time	$t_{on}$	–	6.0	15	ns
Turn-Off Time	$t_{off}$	–	12	15	ns

3. Pulse Test: Pulse Width  $\leq 300\text{ }\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## RESISTIVE SWITCHING

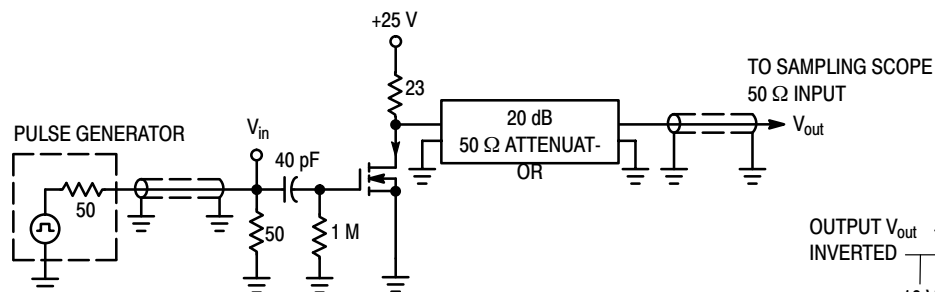


Figure 1. Switching Test Circuit

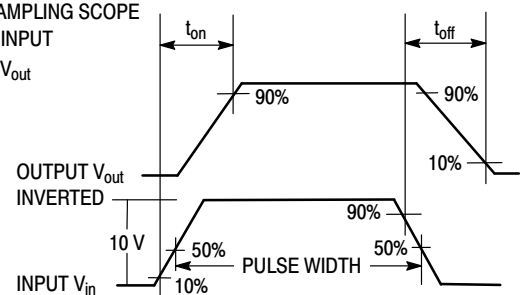


Figure 2. Switching Waveforms

# BS107A

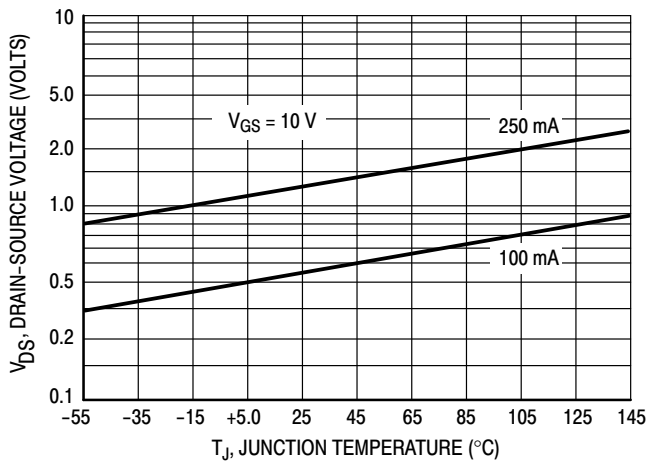


Figure 3. On Voltage versus Temperature

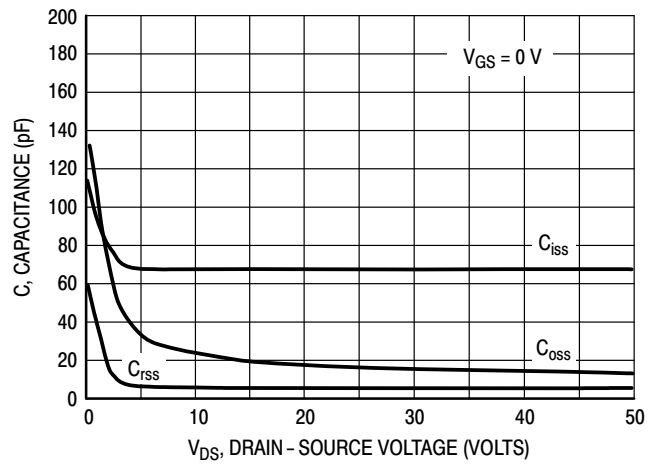


Figure 4. Capacitance Variation

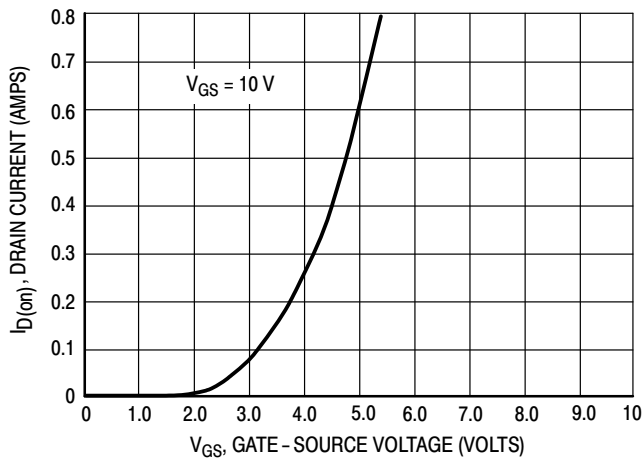


Figure 5. Transfer Characteristic

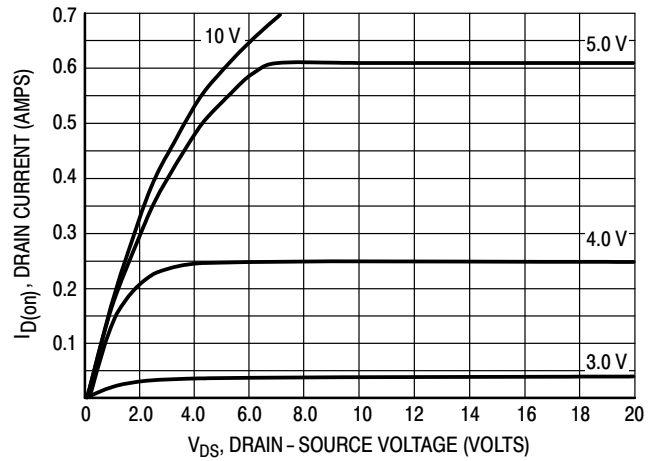


Figure 6. Output Characteristic

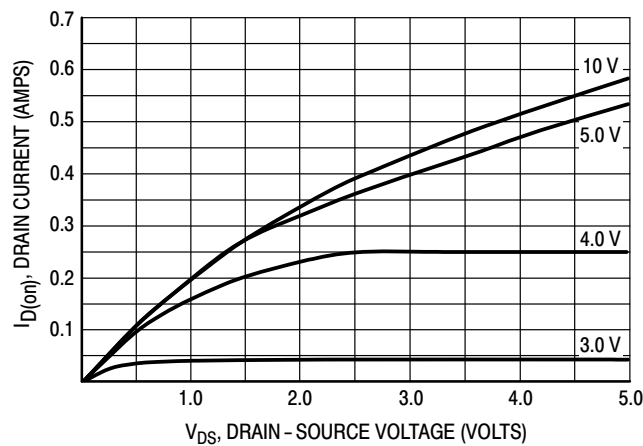
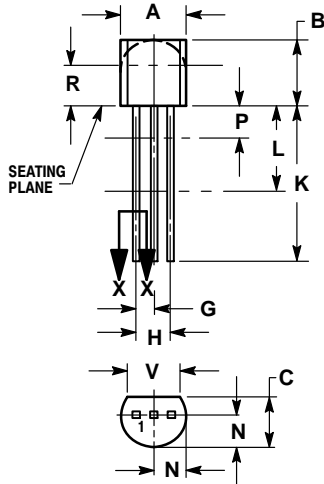


Figure 7. Saturation Characteristic

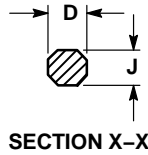
# BS107A

## PACKAGE DIMENSIONS

### TO-92 (TO-226) CASE 29-11 ISSUE AM



STRAIGHT LEAD  
BULK PACK

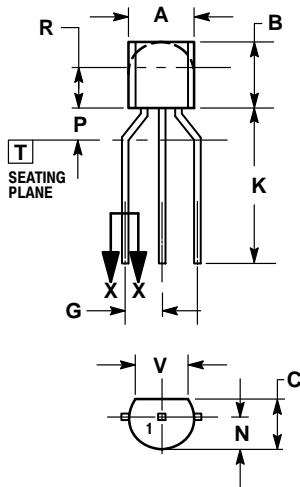


SECTION X-X

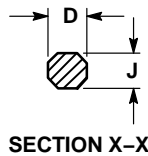
#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD  
TAPE & REEL  
AMMO PACK



SECTION X-X

#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

#### STYLE 30:

1. DRAIN
2. GATE
3. SOURCE

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